





PAD LOCATION

| Pad No. | Pad Name | х | Y |
|------------|----------|-----|-----|
| 1 | GND | 92 | 107 |
| 2 | Output | 899 | 747 |
| 3 | Input | 92 | 747 |

Note:

•Co-ordinates (bottom left co-ordinates comer), μm •Padsize: 96x96 μm^2

PHISICAL CHARACTERISTICS

Wafer Diameter..... 100 ± 0.5 mm; Wafer thickness 280 ± 20μm; Scribe width80 μm; Metallization: Top... Al Bottom... without metallization

ABSOLUTE MAXIMUM RATINGS

Input Voltage Junction Temperature

35V +150°C

ELECTRICAL CHARACTERISTICS IL3480-3.3, IL3480-5.0

Typicals and limits appearing in normal type apply for $TA = TJ = 25^{\circ}C$. Limits appearing in boldface type apply over the entire junction temperature range for operation, -10 to +70°C. (Notes 1, 2)

| Nominal Output Voltage (VNOM) | | | 3.3V | | 5.0V | | | Unite | |
|-------------------------------|------------------|--|--------------|-------------------|--------------|-------------|-------------------|-------------|-------|
| Parameter | Symbol | Conditions | Min | Тур | Max | Min | Тур | Max | Units |
| Output Voltage | Vout | Vin=Vnom+1.5V; 1mA≤lout≤100mA | 3.17 3.14 | 3.3 | 3.43 3.46 | 4.8 4.75 | 5.0 | 5.2 5.25 | V |
| Line Regulation | ∆Vout | Vnom+1.5V ≤Vin≤30V; Iout =1mA | | | 25 | | | 25 | mV |
| Load Regulation | ∆Vout | Vin=Vnom+1.5V; 1mA≤lout≤100mA | | | 50 | | | 50 | mV |
| Ground Pin Current | I _{GND} | Vin=30V No Load | | 3 | 4 | | 3 | 4 | mA |
| Ground Pin Current Change | ΔI_{GND} | Vnom+1.5V ≤Vin≤20V, lout =40mA; Vin=Vnom+5V, | | | 1.4 | | | 1.4 | mA |
| | | 1mA≤lout≤40mA | | | 0.5 | | | 0.5 | mA |
| Dropout Voltage Vin- | lout =10mA; | | | 0.9 1.0 1 1 | | | 0.9 1.0 1 1 | V | |
| | Vou | lout =100mA | | | 1.2 | | | 1.2 | |

Note 1: A typical is the center of characterization data taken with $TA = TJ = 25^{\circ}C$. Typicals are not guaranteed.

Note 2: All limits are guaranteed. All electrical characteristics having room-temperature limits are tested during production

with TA = TJ = 25 °C. All hot and cold limits are guaranteed by correlating the electrical characteristics to process and temperature variations and applying statistical process control.